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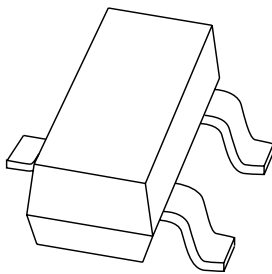
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Kind regards,

Team Nexperia

# DATA SHEET



## **BCW29; BCW30** PNP general purpose transistors

Product data sheet  
Supersedes data of 1999 Apr 13

2004 Jan 13

## PNP general purpose transistors

## BCW29; BCW30

## FEATURES

- Low current (max. 100 mA)
- Low voltage (max. 32 V).

## APPLICATIONS

- General purpose switching and amplification.

## DESCRIPTION

PNP transistor in a SOT23 plastic package.  
NPN complements: BCW31 and BCW32.

## MARKING

TYPE NUMBER	MARKING CODE <sup>(1)</sup>
BCW29	C1*
BCW30	C2*

## Note

1. \* = p : Made in Hong Kong.  
 \* = t : Made in Malaysia.  
 \* = W : Made in China.

## PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector

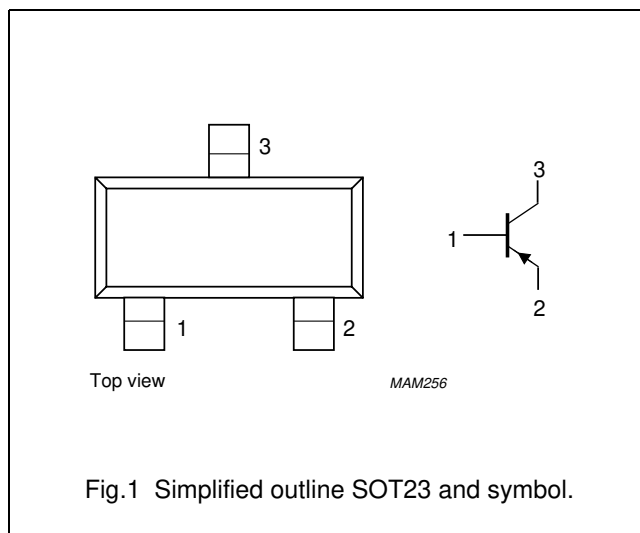


Fig.1 Simplified outline SOT23 and symbol.

## ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BCW29	—	plastic surface mounted package; 3 leads	SOT23
BCW30			

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CBO}$	collector-base voltage	open emitter	—	–32	V
$V_{CEO}$	collector-emitter voltage	open base; $I_C = -2$ mA	—	–32	V
$V_{EBO}$	emitter-base voltage	open collector	—	–5	V
$I_C$	collector current (DC)		—	–100	mA
$I_{CM}$	peak collector current		—	–200	mA
$I_{BM}$	peak base current		—	–200	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25$ °C	—	250	mW
$T_{stg}$	storage temperature		–65	+150	°C
$T_j$	junction temperature		—	150	°C
$T_{amb}$	operating ambient temperature		–65	+150	°C

## PNP general purpose transistors

## BCW29; BCW30

## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	500	K/W

## Note

1. Transistor mounted on an FR4 printed-circuit board.

## CHARACTERISTICS

$T_j = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_{CBO}$	collector cut-off current	$I_E = 0; V_{CB} = -32\text{ V}$	–	–	–100	nA
		$I_E = 0; V_{CB} = -32\text{ V}; T_j = 100\text{ }^{\circ}\text{C}$	–	–	–10	$\mu\text{A}$
$I_{EBO}$	emitter cut-off current	$I_C = 0; V_{EB} = -5\text{ V}$	–	–	–100	nA
$h_{FE}$	DC current gain BCW29 BCW30	$I_C = -10\text{ }\mu\text{A}; V_{CE} = -5\text{ V}$	–	90	–	
			–	150	–	
	DC current gain BCW29 BCW30	$I_C = -2\text{ mA}; V_{CE} = -5\text{ V}$	120	–	260	
			215	–	500	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -10\text{ mA}; I_B = -0.5\text{ mA}$	–	–80	–300	mV
		$I_C = -50\text{ mA}; I_B = -2.5\text{ mA}$	–	–150	–	mV
$V_{BEsat}$	base-emitter saturation voltage	$I_C = -10\text{ mA}; I_B = -0.5\text{ mA}$	–	–720	–	mV
		$I_C = -50\text{ mA}; I_B = -2.5\text{ mA}$	–	–810	–	mV
$V_{BE}$	base-emitter voltage	$I_C = -2\text{ mA}; V_{CE} = -5\text{ V}$	–600	–	–750	mV
$C_c$	collector capacitance	$I_E = I_e = 0; V_{CB} = -10\text{ V}; f = 1\text{ MHz}$	–	4.5	–	pF
$f_T$	transition frequency	$I_C = -10\text{ mA}; V_{CE} = -5\text{ V}; f = 100\text{ MHz}$	100	–	–	MHz
F	noise figure	$I_C = -200\text{ }\mu\text{A}; V_{CE} = -5\text{ V}; R_S = 2\text{ k}\Omega; f = 1\text{ kHz}; B = 200\text{ Hz}$	–	–	10	dB

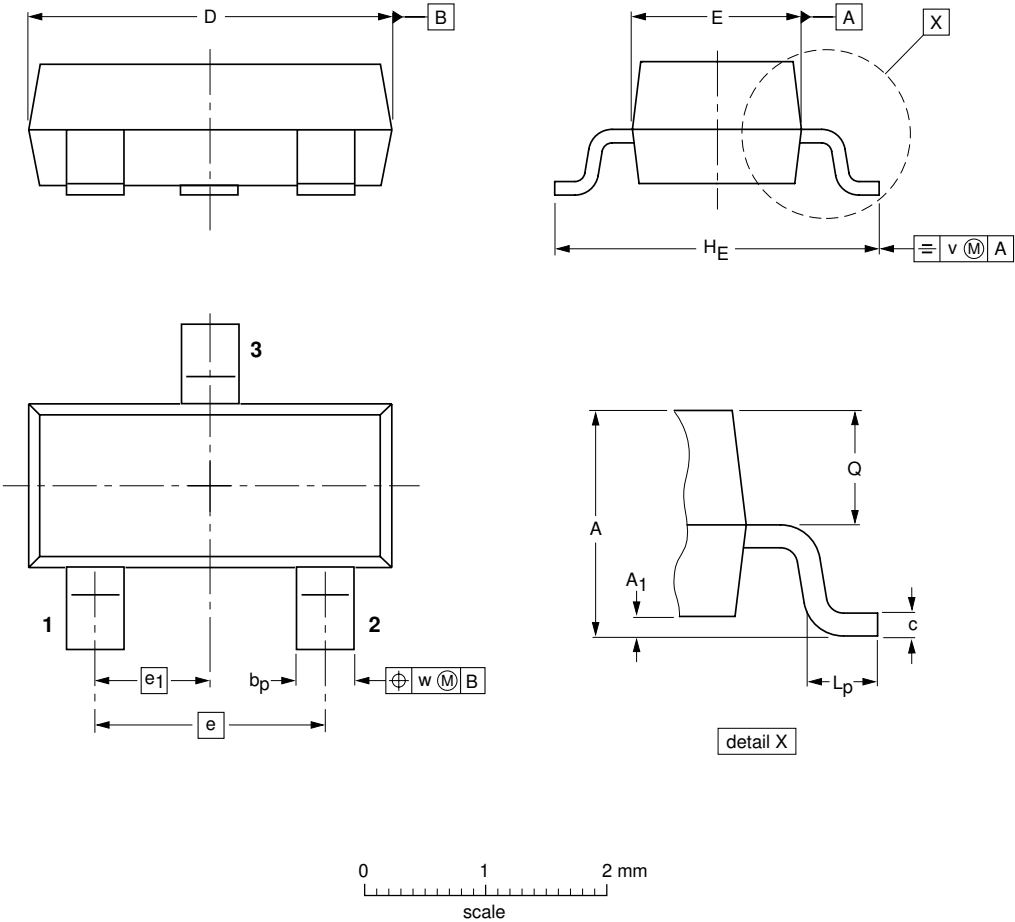
PNP general purpose transistors

BCW29; BCW30

PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads

SOT23



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max.	b <sub>p</sub>	c	D	E	e	e <sub>1</sub>	H <sub>E</sub>	L <sub>p</sub>	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT23		TO-236AB				04-11-04 06-03-16

## PNP general purpose transistors

## BCW29; BCW30

## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

## Notes

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# ***NXP Semiconductors***

## **Customer notification**

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## **Contact information**

For additional information please visit: **<http://www.nxp.com>**

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